# Product Change Notification - KSRA-19VAHD748

Date: 27 Apr 2017

**Notification text:** 

**Product Category:** 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

**Notification subject:** CCB 2924 and 2924.001 Initial Notice: Qualification of CuPdAu bond wire in selected products of

the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site

PCN Status:

Initial notification

#### Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

#### **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site

### Pre Change:

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

#### Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

# Pre and Post Change Summary:

	Pre Ch	ange	Post Change				
Assembly Site	NSEB Asse	embly Site	NSEB Assembly Site				
Wire material	Au V	Vire	CuPdAu Wire				
Die attach material	8200T	8600	8600				
Molding compound material	G770HCD	G700LTD	G700LTD				
Lead frame material	C19	94	C194				

# Impacts to Data Sheet:

None

#### **Change Impact:**

None

### Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

# **Change Implementation Status:**

In Progress

# **Estimated Qualification Completion Date:**

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

#### Time Table Summary:

		April 2017					>	October 2017				
Workweek	13	14	15	16	17	18		40	41	42	43	44
Initial PCN Issue Date					Х							
Qual Report Availability									Χ			
Final PCN Issue Date									Χ			

# Method to Identify Change:

Traceability code

# **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

#### **Revision History:**

April 27, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): PCN\_KSRA-19VAHD748\_Affected CPN.pdf

PCN\_KSRA-19VAHD748\_Qual Plan.pdf PCN\_KSRA-19VAHD748\_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

# **Terms and Conditions:**

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PCN\_KSRA-19VAHD748 -CCB 2924 and 2924.001 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technology available in 28L QFN-S package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

PCN_KSRA-19VAHD748
CATALOG_PART_NBR
DSPIC30F1010-20E/MM
DSPIC30F1010-30I/MM
DSPIC30F2010-20E/MM
DSPIC30F2010-20I/MM
DSPIC30F2010-30I/MM
DSPIC30F2010T-20E/MM
DSPIC30F2010T-20I/MM
DSPIC30F2010T-30I/MM
DSPIC30F2010T-30V/MMA31
DSPIC30F2020-20E/MM
DSPIC30F2020-30I/MM
DSPIC30F2020T-30I/MM
PIC18F2331-E/MM
PIC18F2331-I/MM
PIC18F2331T-I/MM
PIC18F2431-E/MM
PIC18F2431-I/MM
PIC18F2431T-E/MM
PIC18F2431T-I/MM
PIC18F2480-E/ML
PIC18F2480-I/ML
PIC18F2480-I/MLC01
PIC18F2480T-E/ML
PIC18F2480T-I/ML
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